

PC10904HG

Component Metallization

Description

PC10904HG is a high performance silver conductor designed for metallizing ceramic component devices. The rheology of PC10904HG is optimized for dipping and spraying methods of application. PC10904HG is a higher green strength version of PC10904.

Key Features

- High green strength Excellent conductivity High adhesion to various oxide substrates Optimized for dipping and spraying applications



Typical Properties

Viscosity	2.7 – 3.3 kcps Brookfield RVT, Spindle #4 @ 20 rpm, 25°C
Resistivity	< 1.5 milliohms per square at 25 microns fired film thickness.
Solderability	3 seconds dip Sn62/Pb36/Ag2, 200°C Excellent
Solder Leaching	Sn62/Pb36/Ag2, 230°C 10mil wide conductor trace < 50% loss

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Recommended Processing Guide

Printing Parameters	The material should be thoroughly shaken before use. Apply the material by dipping or spraying.
Drying Temperature	125-150°C for 5-10 minutes.
Process Temperature (TDS)	850°C - 925°C peak temperature Dwell time of 5-10minutes dwell time.
Film Thickness	11-13 microns
Recommended Thinner	Heraeus RV-404

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Warranty

Material guaranteed to meet specifications for 6 months from date of manufacturing with proper storage.

Storage

Store in a dry location at 5 – 25°C. DO NOT REFRIGERATE. Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

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